

June 2014

1.2W AUDIO POWER AMPLIFIER WITH ACTIVE-LOW SHUTDOWN MODE

DESCRIPTION

The IS31AP4990D has been designed for demanding audio applications such as mobile phones and permits the reduction of the number of external components.

It is capable of delivering 1.2W of continuous RMS output power into an 8Ω load @ 5V.

An externally-controlled shutdown mode reduces the supply current to less than $1\mu A$. It also includes internal thermal shutdown protection.

The unity-gain stable amplifier can be configured by external gain setting resistors.

FEATURES

- Operating from V_{CC} = 2.7V ~ 5.5V
- 1.2W output power @ V_{CC} = 5V, THD+N= 1%,
- f = 1 kHz, with 8Ω load
- Ultra-low consumption in shutdown mode (1µA)
- Near-zero pop & click
- Ultra-low distortion
- Unity gain stable
- UTQFN-9L (1.5mm × 1.5mm) package

APPLICATIONS

- Mobile phones
- PDAs
- Portable electronic devices
- Notebook computer



TYPICAL APPLICATION CIRCUIT

Figure 1 Typical Application Circuit (Single-ended Input)





Figure 2 Typical Application Circuit (Differential Input)



PIN CONFIGURATION

Package	Pin Configuration (Top View)			
UTQFN-9L	• IN- OUT- IN+ (A1) (A2) (A3) GND GND VCC (B1) (B2) (B3) BYPASS OUT+ SDB (C1) (C2) (C3)			

PIN DESCRIPTION

No.	Pin	Function Description		
A1	IN-	Negative input of the first amplifier. Connected to the feedback resistor $R_{\text{F-}}$ and to the input resistor $R_{\text{IN-}}$		
A2	OUT-	Negative output. Connected to the load and to the feedback resistor $R_{F}\text{.}$		
A3	IN+	Positive input of the first amplifier.		
B1,B2	GND	Ground.		
B3	VCC	Supply voltage.		
C1	BYPASS	Bypass capacitor pin which provides the common mode voltage (V $_{\rm CC}/2).$		
C2	OUT+	Positive output. Connected to the load.		
C3	SDB	The device enters in shutdown mode when a low level is applied on this pin.		



ORDERING INFORMATION Industrial Range: -40°C to +85°C

Order Part No.	Package	QTY/Reel		
IS31AP4990D-UTLS2-TR	UTQFN-9, Lead-free	3000		

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a.) the risk of injury or damage has been minimized;

b.) the user assume all such risks; and

c.) potential liability of Lumissil Microsystems is adequately protected under the circumstances



ABSOLUTE MAXIMUM RATINGS

Supply voltage, V _{CC}	-0.3V ~ +6.0V
Voltage at any input pin	$-0.3V \sim V_{CC} + 0.3V$
Maximum junction temperature, T _{JMAX}	+150°C
Storage temperature range, T _{STG}	-65°C ~ +150°C
Operating temperature range, T _A	-40°C ~ +85°C
ESD (HBM)	±7kV
ESD (CDM)	±500V

Note: Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other condition beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

ELECTRICAL CHARACTERISTICS

 T_A = -40°C ~ +85°C, V_{CC} = 2.7V ~ 5.5V, unless otherwise noted. Typical value are T_A = +25°C.

Symbol	Parameter	Condition			Min.	Тур.	Max.	Unit	
V _{CC}	Power supply			2.7		5.5	V		
I _{cc} (Ouissant surrant	V_{CC} = 5V, V_{IN} = 0V, I_O = 0A, no load			3.8	6.4	mA		
		V_{CC} = 3V, V_{IN} = 0V, I_O = 0A, no load				2.8		5.1	
I _{SD}	Shutdown current	V _{SDB} = GNI	D, no load				1	μA	
V _{IH}	Shutdown voltage input high			1.4			V		
V _{IL}	Shutdown voltage input low					0.4	V		
V _{OS}	Output offset voltage					25	mV		
Po	Output power (8Ω)		THD+N =	1%, f = 1kHz		1.20		W	
		$V_{\rm CC} = 5V$	THD+N =	= 10%, f = 1kHz		1.50			
		N/ 0)/	THD+N =	1%, f = 1kHz		0.418			
		$V_{\rm CC} = 3V$	THD+N =	= 10%, f = 1kHz		0.525			
		$V_{CC} = 5V, C_{BYPASS} = 1\mu F$			115				
t _{wu} Wake-up tin	vvake-up time (Note 1)	V_{CC} = 3V, C_{BYPASS} = 1 μ F			102		ms		
THD+N Total harmonic of noise (Note 1)	Total harmonic distortion +	V _{CC} = 5V, F	P _o = 0.5Wrr	ns, f = 1kHz		0.23		0/	
	noise (Note 1)	V _{CC} = 3V, Po = 0.3Wrms, f = 1kHz			0.15		%		
PSRR	Power supply rejection ratio (Note 1)	$ \begin{array}{c} V_{CC} = 5V & f = 217Hz \\ \hline V_{Ripple p-p} = 200mV & f = 1kHz \\ \hline V_{CC} = 3.6V, 4.2V & f = 217Hz \\ \hline V_{Ripple p-p} = 200mV & f = 217Hz \\ \hline Input grounded & f = 1kHz \end{array} $			61				
				f = 1kHz		65		dB	
				f = 217Hz		62			
				f = 1kHz		66			

Note 1: Guaranteed by design.











Figure 9 Efficiency vs. Output Power

APPLICATION INFORMATION

BTL CONFIGURATION PRINCIPLE

The IS31AP4990D is a monolithic power amplifier with a BTL output type. BTL (bridge tied load) means that each end of the load is connected to two single-ended output amplifiers. Thus, we have:

Single-ended output
$$1 = V_{OUT+} = V_{OUT} (V)$$

Single ended output 2 = V_{OUT} = - V_{OUT} (V)

and $V_{OUT+} - V_{OUT-} = 2V_{OUT} (V)$

The output power is:

$$P_{OUT} = \frac{\left(2V_{OUT_{RMS}}\right)^2}{R_L}$$

For the same power supply voltage, the output power in BTL configuration is four times higher than the output power in single ended configuration.

GAIN IN A TYPICAL APPLICATION SCHEMATIC

The typical application schematic is shown in Figure 1 on page 1.

In the flat region (no C_{IN} effect), the output voltage of the first stage is (in Volts):

$$V_{OUT-} = (-V_{IN}) \frac{R_F}{R_{IN}}$$

For the second stage: $V_{OUT+} = -V_{OUT-}(V)$

The differential output voltage is (in Volts):

$$V_{OUT+} - V_{OUT-} = 2V_{IN} \frac{R_F}{R_{IN}}$$

The differential gain, G_v, in shourt, is given by:

$$G_{v} = \frac{V_{OUT+} - V_{OUT-}}{V_{IN}} = 2\frac{R_{F}}{R_{IN}}$$

 V_{OUT^+} is in phase with V_{IN} and V_{OUT^-} is phased 180° with V_{IN} . This means that the positive terminal of the loudspeaker should be connected to V_{OUT^+} and the negative to V_{OUT^-} .

LOW AND HIGH FREQUENCY RESPONSE

In the low frequency region, C_{IN} starts to have an effect. C_{IN} forms with R_{IN} a high-pass filter with a -3dB cut-off frequency. f_{CL} is in Hz.

$$f_{CL} = \frac{1}{2\pi R_{IN} C_{IN}}$$

In the high frequency region, you can limit the bandwidth by adding a capacitor (C_F) in parallel with R_F. It forms a low-pass filter with a -3dB cut-off frequency. f_{CH} is in Hz.

$$f_{CH} = \frac{1}{2\pi R_F C_F}$$

DECOUPLING OF THE CIRCUIT

Two capacitors are needed to correctly bypass the IS31AP4990D: a power supply bypass capacitor $C_{\rm S}$ and a bias voltage bypass capacitor $C_{\rm BYPASS}.$

 $C_{\rm S}$ has particular influence on the THD+N in the high frequency region (above 7kHz) and an indirect influence on power supply disturbances. With a value for $C_{\rm S}$ of 1µF, you can expect THD+N levels similar to those shown in the datasheet.

In the high frequency region, if C_S is lower than 1µF, it increases THD+N and disturbances on the power supply rail are less filtered.

On the other hand, if C_s is higher than 1µF, those disturbances on the power supply rail are more filtered.

 C_{BYPASS} has an influence on THD+N at lower frequencies, but its function is critical to the final result of PSRR (with input grounded and in the lower frequency region).

If C_{BYPASS} is lower than 1µF, THD+N increases at lower frequencies and PSRR worsens.

If C_{BYPASS} is higher than 1µF, the benefit on THD+N at lower frequencies is small, but the benefit to PSRR is substantial.

Note that $C_{\rm IN}$ has a non-negligible effect on PSRR at lower frequencies. The lower the value of $C_{\rm IN},$ the higher the PSRR is.

WAKE-UP TIME (twu)

When the SDB pin is released to put the device ON, the bypass capacitor C_{BYPASS} will not be charged immediately. As C_{BYPASS} is directly linked to the bias of the amplifier, the bias will not work properly until the C_{BYPASS} voltage is correct. The time to reach this voltage is called wake-up time or t_{WU} and specified in the electrical characteristics table with $C_{BYPASS} = 1\mu F$.

POP PERFORMANCE

Pop performance is intimately linked with the size of the input capacitor C_{IN} and the bias voltage bypass capacitor $C_{\text{BYPASS}}.$

The size of C_{IN} is dependent on the lower cut-off frequency and PSRR values requested. The size of C_{BYPASS} is dependent on THD+N and PSRR values requested at lower frequencies.

Moreover, C_{BYPASS} determines the speed with which the amplifier turns ON.



CLASSIFICATION REFLOW PROFILES

Profile Feature	Pb-Free Assembly		
Preheat & Soak Temperature min (Tsmin) Temperature max (Tsmax) Time (Tsmin to Tsmax) (ts)	150°C 200°C 60-120 seconds		
Average ramp-up rate (Tsmax to Tp)	3°C/second max.		
Liquidous temperature (TL) Time at liquidous (tL)	217°C 60-150 seconds		
Peak package body temperature (Tp)*	Max 260°C		
Time (tp)** within 5°C of the specified classification temperature (Tc)	Max 30 seconds		
Average ramp-down rate (Tp to Tsmax)	6°C/second max.		
Time 25°C to peak temperature	8 minutes max.		



Figure 10 Classification Profile



PACKAGING INFORMATION

UTQFN-9L



Note: All dimensions in millimeters unless otherwise stated.

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IS31AP4990D-UTLS2-TR